

SOT1940-1

PQFP-E-172; plastic quad flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.

3 August 2023

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HDQFP172
Package type industry code	PQFP-E-172
Package style descriptive code	QFP (quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MO-355 F
Mounting method type	S (surface mount)
Issue date	16-05-2023
Manufacturer package code	98ASA01107D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	16	-	mm
package width	-	16	-	mm
seated height	-	1.65	1.75	mm
package height	1.5	1.55	1.6	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	172	-	



PQFP-E-172; plastic qual flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.

2 Package outline

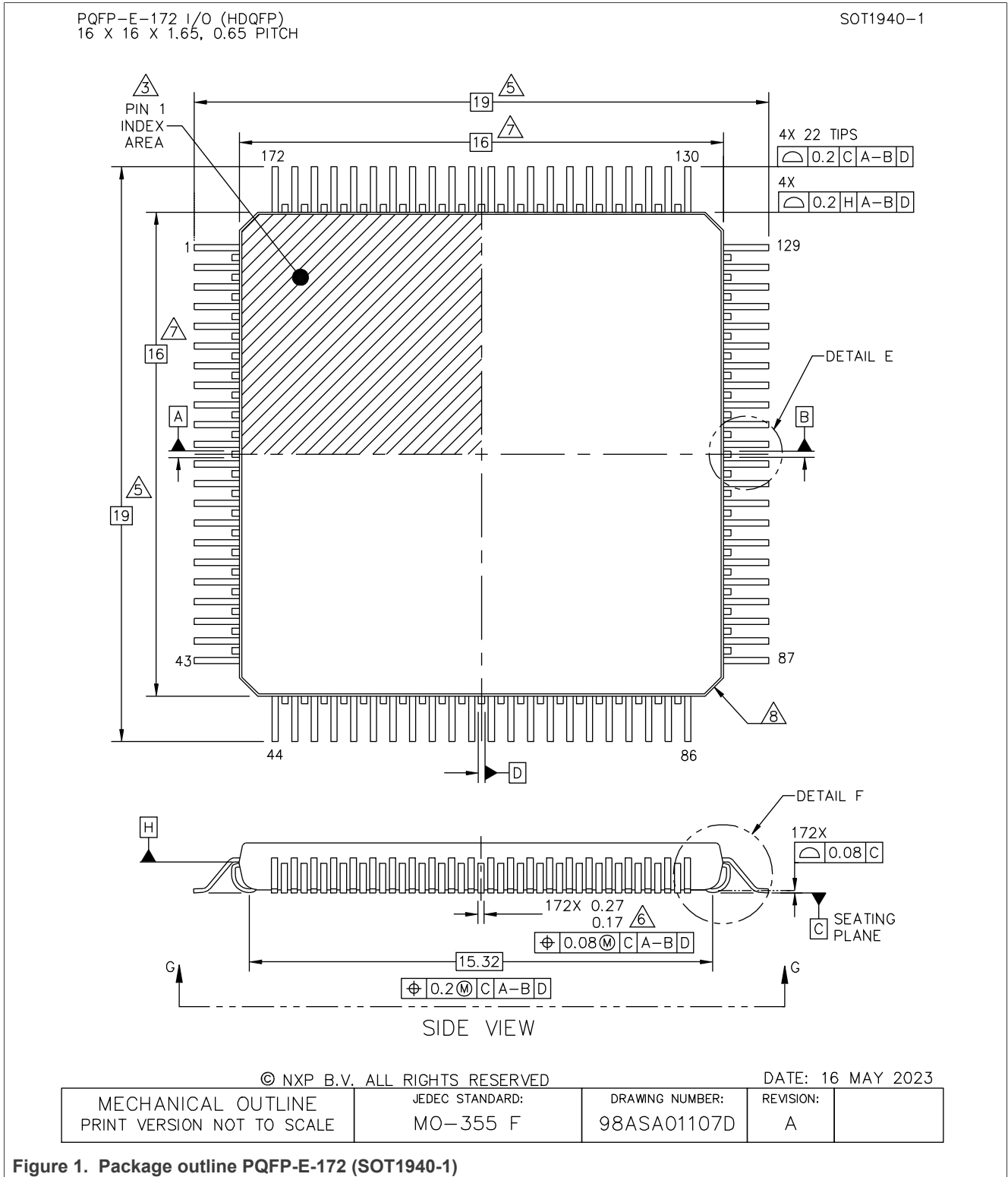
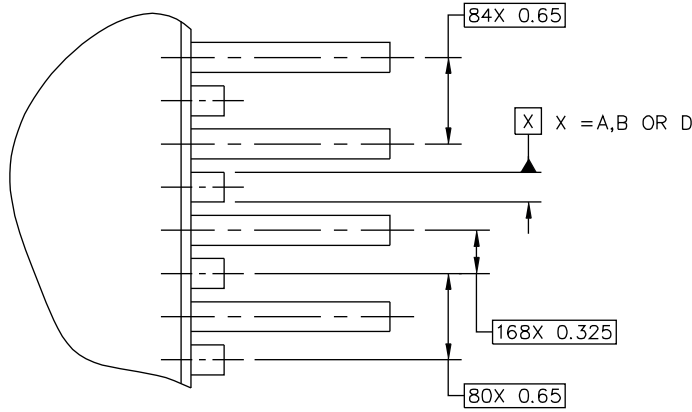


Figure 1. Package outline PQFP-E-172 (SOT1940-1)

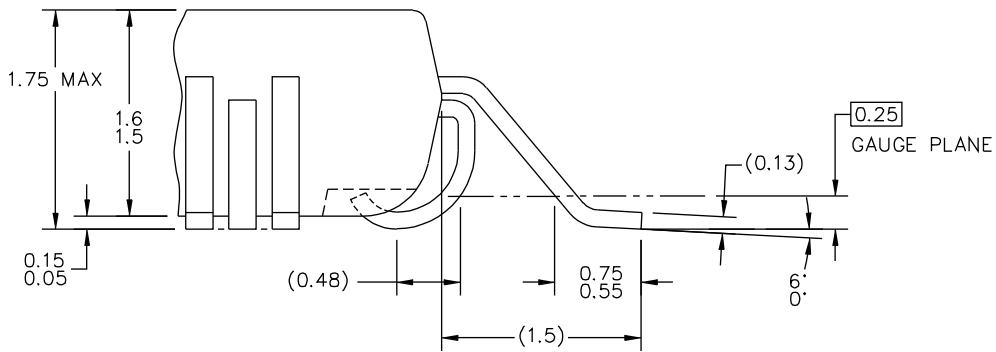
PQFP-E-172; plastic qual flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.

PQFP-E-172 I/O (HDQFP)
16 X 16 X 1.65, 0.65 PITCH

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DETAIL E



DETAIL F

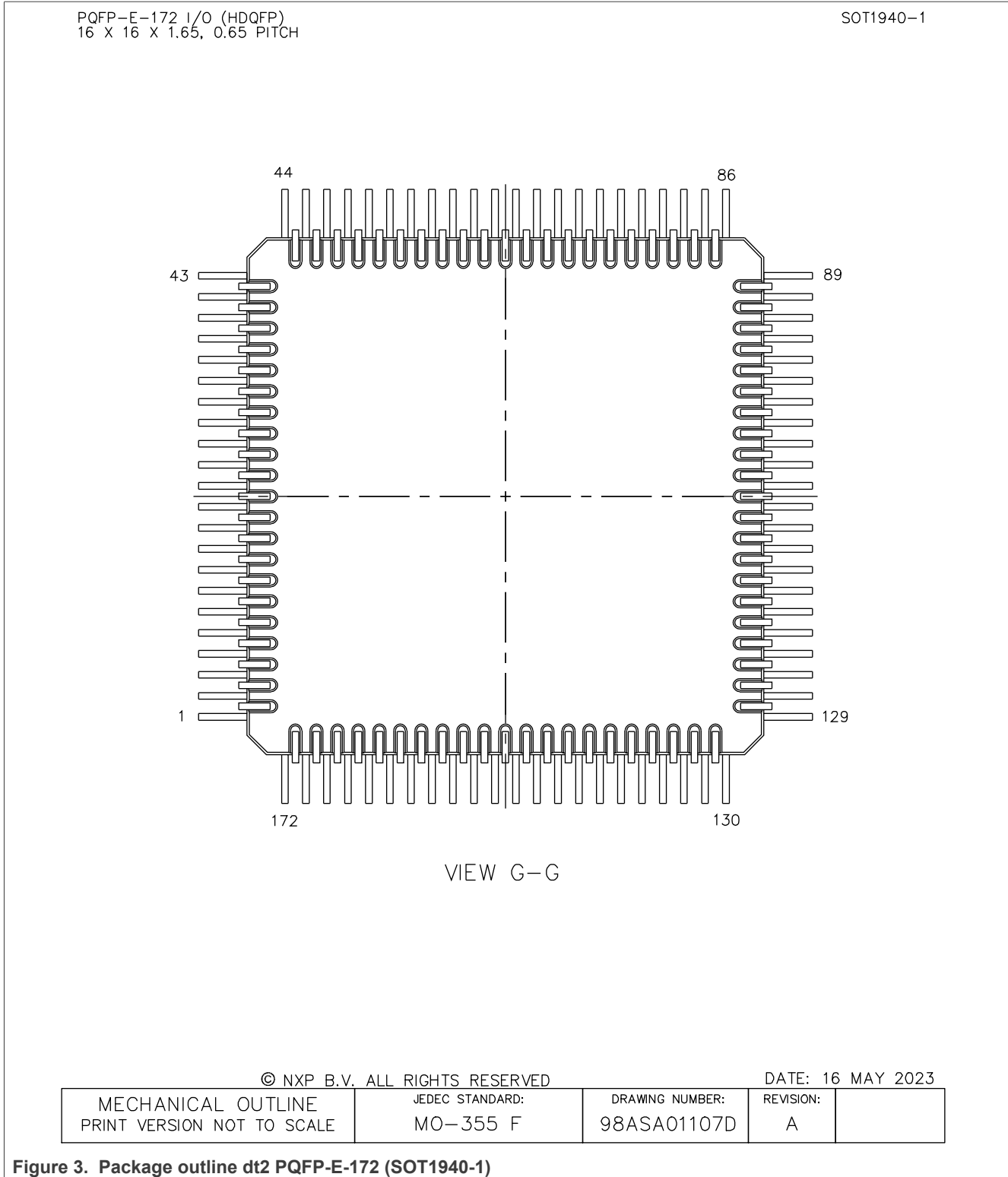
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DATE: 16 MAY 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	JEDEC STANDARD: MO-355 F	DRAWING NUMBER: 98ASA01107D	REVISION: A	
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Figure 2. Package outline dt1 PQFP-E-172 (SOT1940-1)

PQFP-E-172; plastic qual flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.



PQFP-E-172; plastic quad flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.

3 Soldering

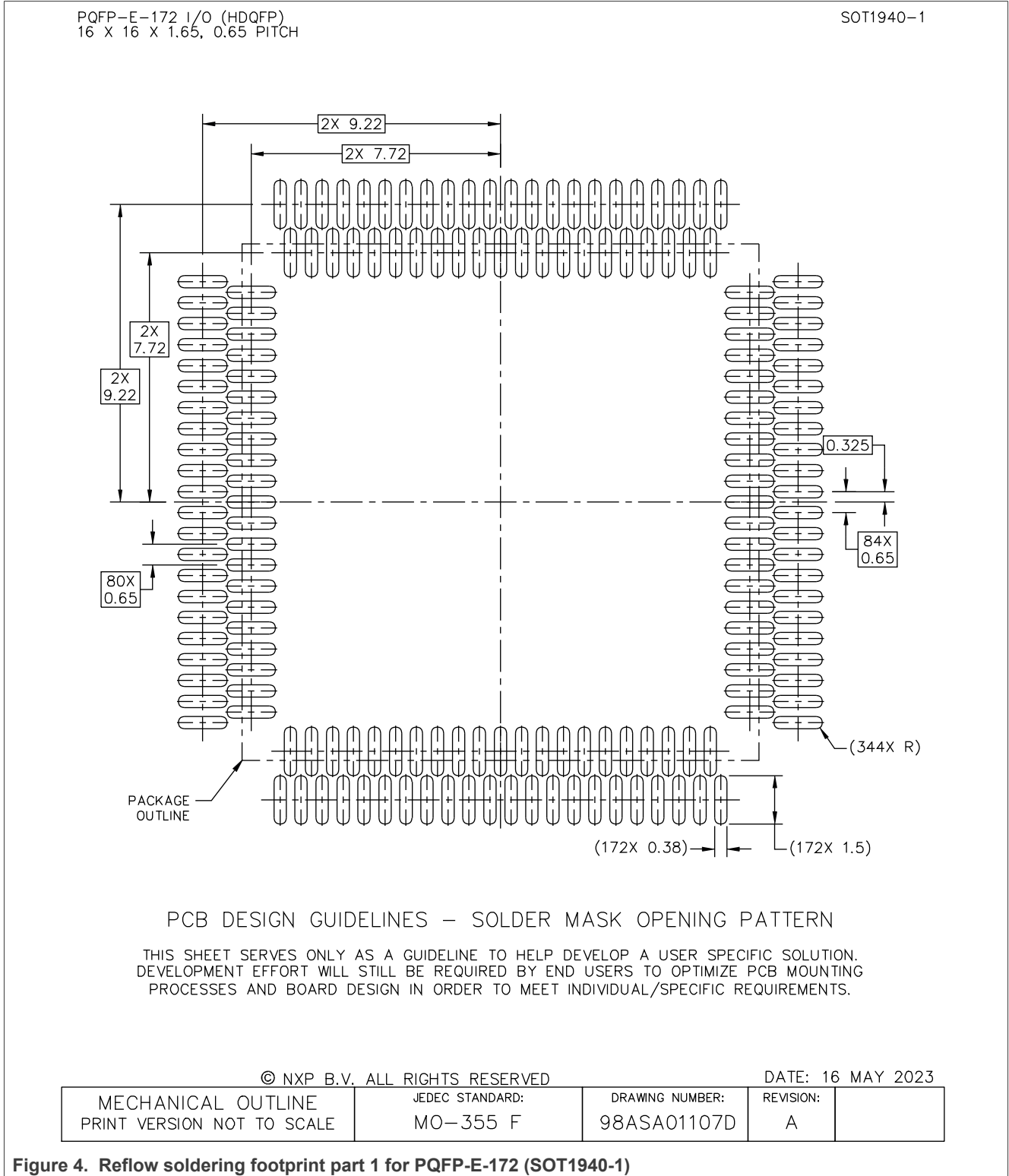


Figure 4. Reflow soldering footprint part 1 for PQFP-E-172 (SOT1940-1)

PQFP-E-172; plastic quad flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.

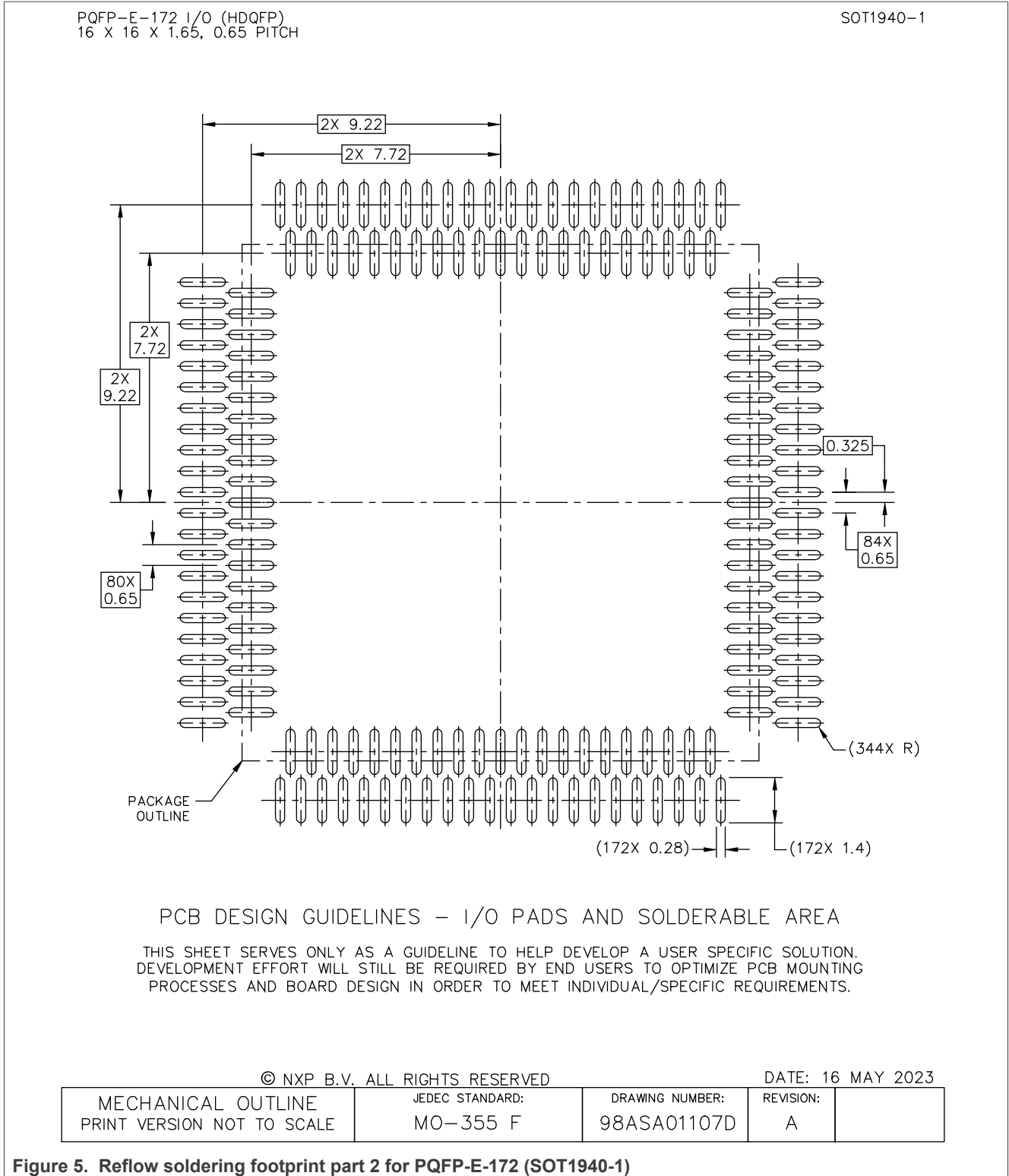
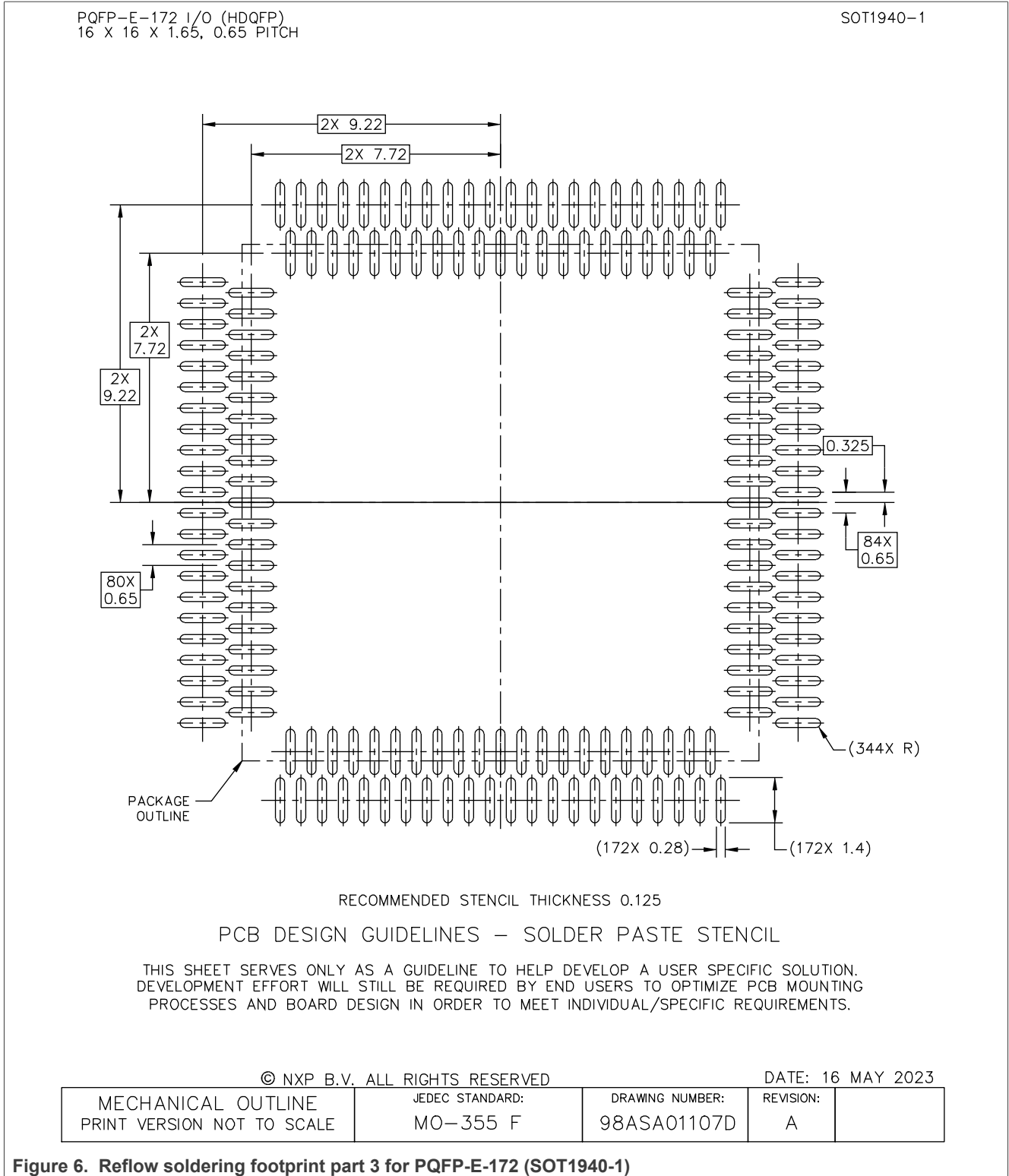


Figure 5. Reflow soldering footprint part 2 for PQFP-E-172 (SOT1940-1)

PQFP-E-172; plastic quad flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.



PQFP-E-172; plastic qual flat package; 172 terminals, 0.65 mm pitch, 16 mm x 16 mm x 1.65 mm body.

PQFP-E-172 I/O (HDQFP)
16 X 16 X 1.65, 0.65 PITCH

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

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Figure 7. Package outline note PQFP-E-172 (SOT1940-1)

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4 Legal information

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